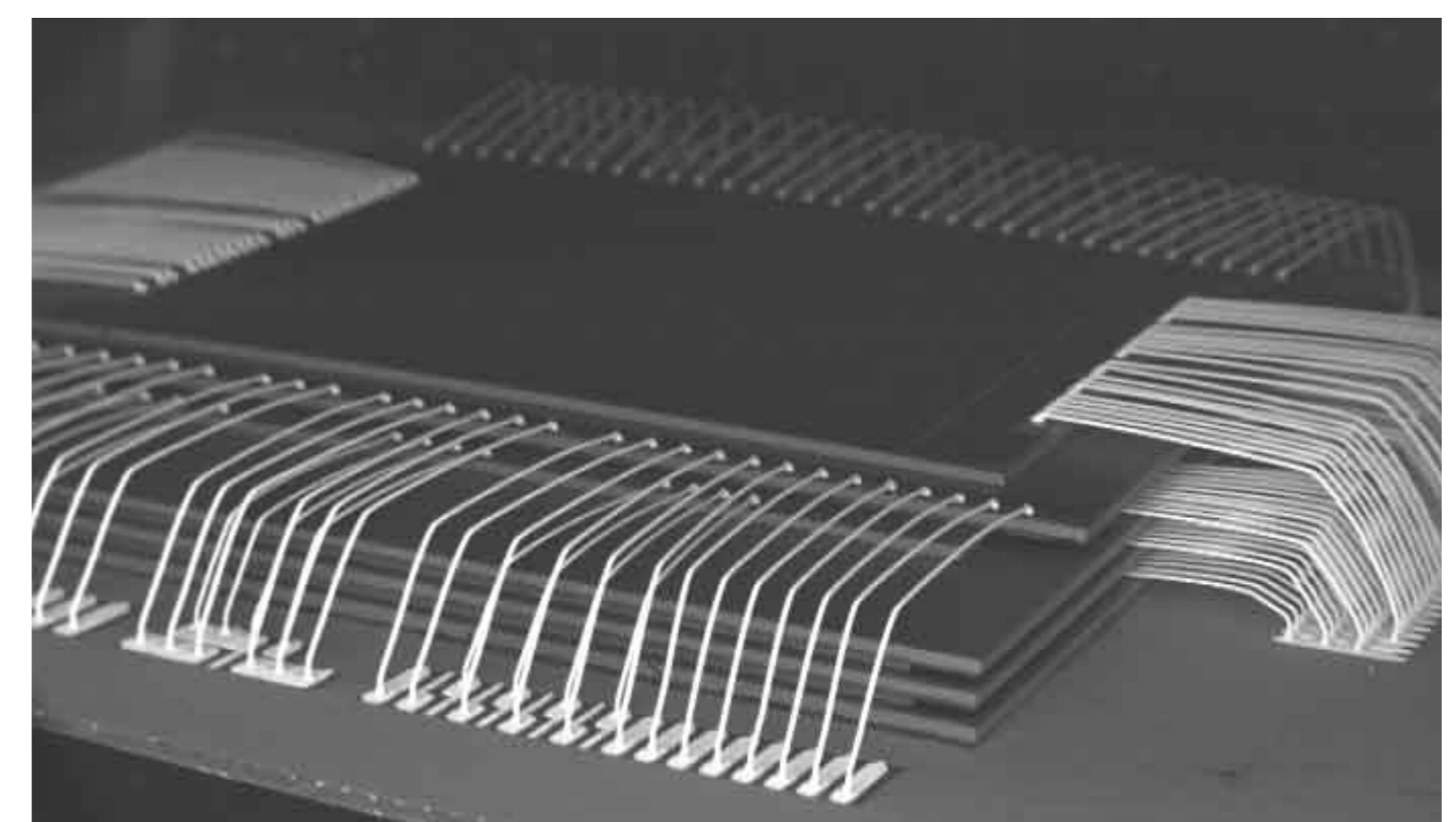
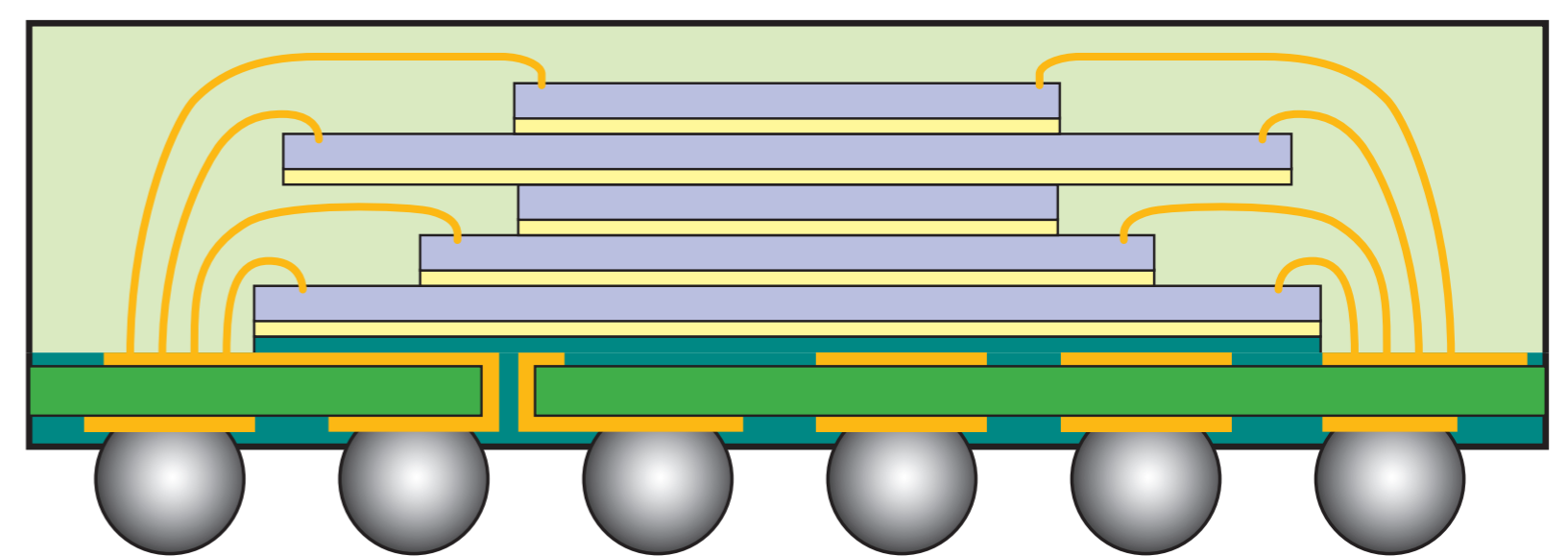
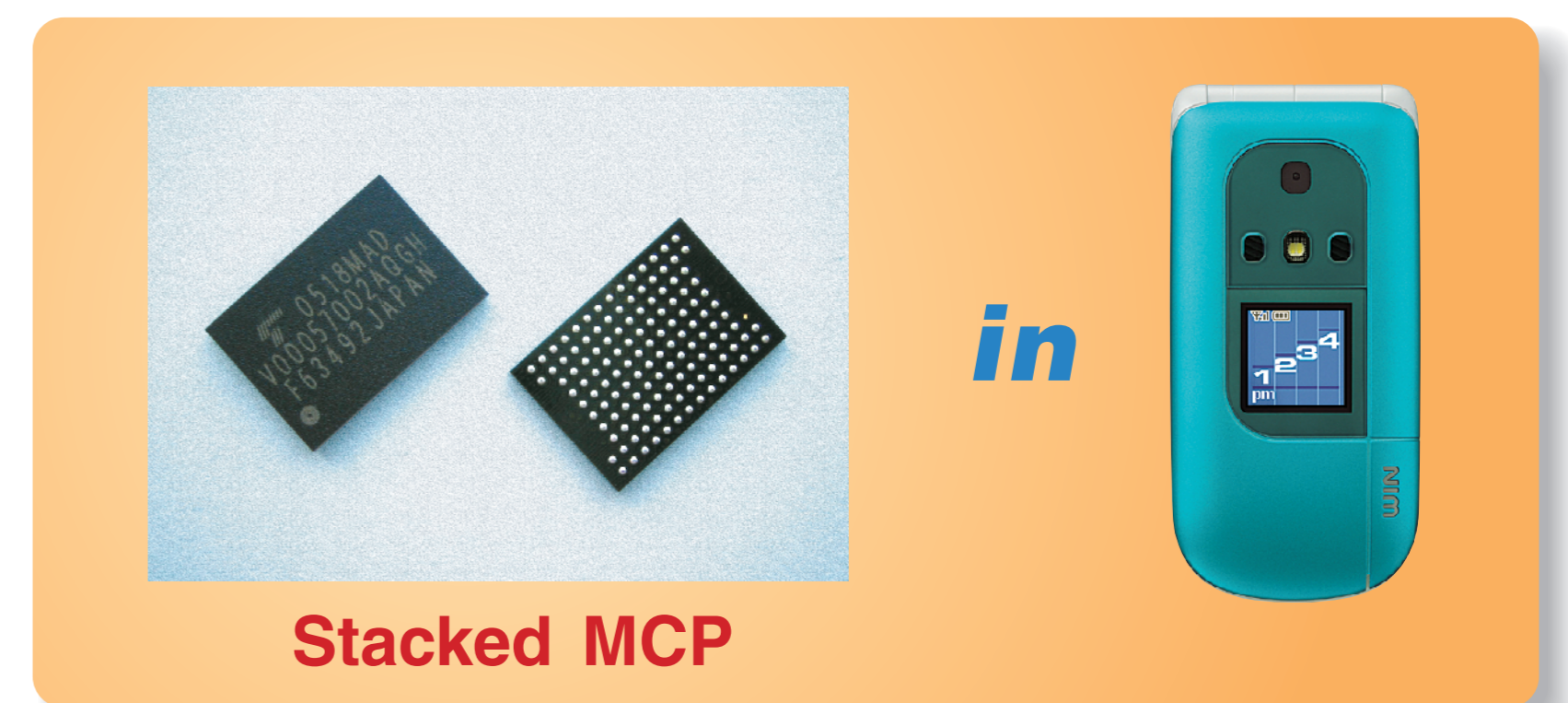
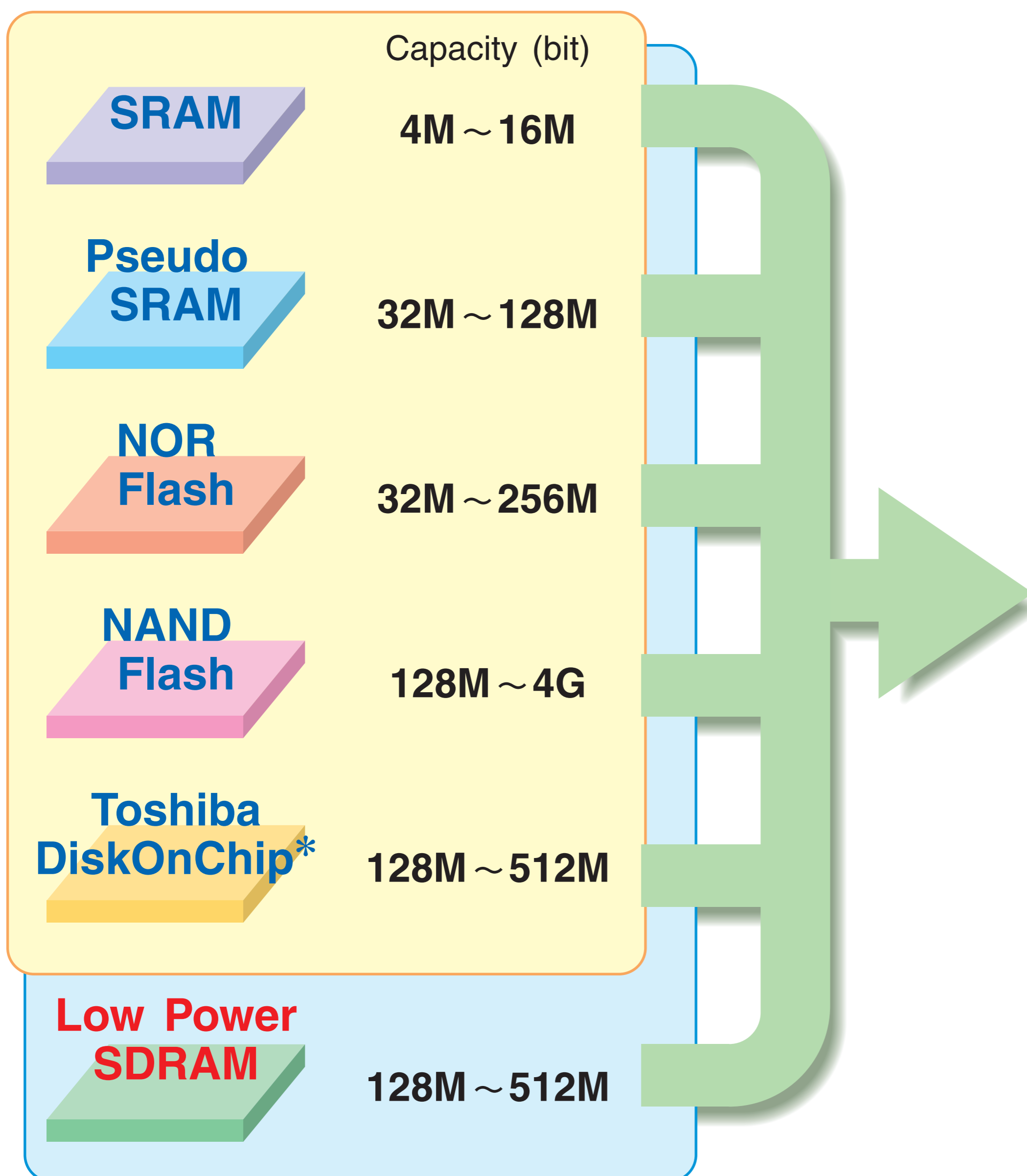


## 适用于手机的堆叠多芯片封装 for Mobile Applications

Large capacity, compact size,  
and thin package optimized for cell phones

Large capacity, compact size,  
and thin package optimized for cell phones

Compact size and thin package optimized  
for cell phones  
(Stacked Multi-Chip Package)



Using the latest packaging technology to realize a larger capacity, higher chip density, and thinner package design

- 9-layer stack (including spacers) with 1.4-mm height
- 5-layer stack (including spacers) with 1.0-mm height
- 0.65 mm ball pitch for enabling a 3-bus (low-speed, high-speed, and NAND) design
- Lineup with chip sizes of 11-14mm, 10-13.5mm, 9-12mm, and 7-10mm

Stacking of large-capacity  
NAND flash chip (4 Gbit and larger)  
for also enabling silicon audio function

### ● Low voltage design (low power design)

SRAM, PSRAM, NOR, NAND, SDRAM: Lineup of 1.8V-Only Supply Voltage Products

\*Toshiba DiskOnChip: NAND Flash memory with controller that was jointly developed with M-Systems based on Toshiba NAND Flash

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